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ATTORNEY DOCKET: CPAC 1029-5

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Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450,
Alexandria, VA 22313-1450 at
(571) 273-8300 on 24 January 2006.

Signed:


Paula Faulk Hurley

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Marcos Kamezos

Application No.: 10/681,583

Filed: 08 October 2003

Title: Semiconductor multi-package module
having inverted second package stacked over
die-down flip-chip ball grid array (BGA)
package

Attorney Docket No.: CPAC 1029-5

Examiner: Alonzo Chambliss

Group: 2814

Confirmation No.: 6814

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SUBMISSION OF PRIOR ART AFTER NOTICE OF ALLOWANCE

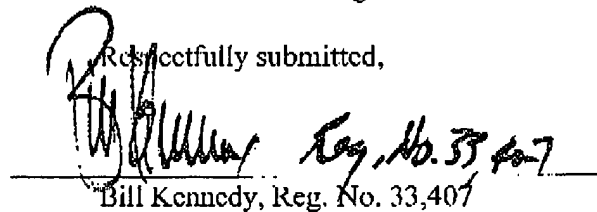
Sir:

Applicants submit the below-listed document to be placed in the file:

- Pedron, Jr.; U. S. Patent No. 6,818,980 issued 16 November 2004 for "Stacked Semiconductor Package and Method of Manufacturing Same".

Respectfully submitted,

Date: 24 January 2006


Bill Kennedy, Reg. No. 33,407

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